Special Issue

Smart Manufacturing Networks for Industry 4.0

Message from the Guest Editors

Smart Manufacturing Networks for Industry 4.0 namely the integration of both the physical and virtual network world, is the trend of the global development era of production manufacturing. Effectively strengthening and improving the efficiency and performance of Smart Manufacturing Networks for Industry 4.0 by reinforcing operational reliability and deepening the interaction between humans and machines is crucial and is a top priority. This Special Collection aims to provide an international open access forum for the development, research, demonstration, and analysis of innovative knowledge along with information related to all topics in the collaboration of Soft Computing in Smart Manufacturing Networks for Industry 4.0. If you are interested, you can also submit your work directly via the following link: https://susy.mdpi.com/user/manuscripts/upload/08669c19ccd89ad9d176bd6096de8632?form%5Bjournal_id%5D=90&form%5Bspecial_issue_id%5D=89058

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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